

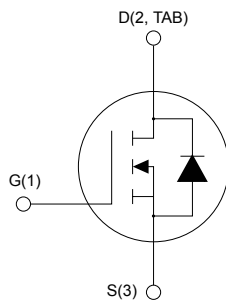
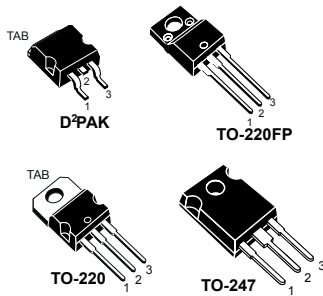


STB28NM50N, STF28NM50N STP28NM50N, STW28NM50N

Datasheet

N-channel 500 V, 135 mΩ typ., 21 A MDmesh II Power MOSFETs
in D²PAK, TO-220FP, TO-220 and TO-247 packages

Features



AM01475v1_noZen

Order code	V _{DS}	R _{DS(on)} max.	I _D
STB28NM50N	500 V	158 mΩ	21 A
STF28NM50N			
STP28NM50N			
STW28NM50N			

- 100% avalanche tested
- Low input capacitance and gate charge
- Low gate input resistance

Applications

- Switching applications

Description

These devices are N-channel Power MOSFETs developed using the second generation of MDmesh technology. These revolutionary Power MOSFETs associate a vertical structure to the company's strip layout to yield one of the world's lowest on-resistance and gate charge. They are therefore suitable for the most demanding high-efficiency converters.



Product status links

[STB28NM50N](#)

[STF28NM50N](#)

[STP28NM50N](#)

[STW28NM50N](#)

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		D ² PAK TO-220 TO-247	TO-220FP	
V _{DS}	Drain-source voltage	500		V
V _{GS}	Gate-source voltage	±25		V
I _D	Drain current (continuous) at T _C = 25 °C	21	21 ⁽¹⁾	A
I _D	Drain current (continuous) at T _C = 100 °C	13	13 ⁽¹⁾	A
I _{DM} ⁽²⁾	Drain current (pulsed)	84	84 ⁽¹⁾	A
P _{TOT}	Total power dissipation at T _C = 25 °C	150	35	W
dv/dt ⁽³⁾	Peak diode recovery voltage slope	15		V/ns
V _{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink (t = 1 s; T _C = 25 °C)		2.5	kV
T _{stg}	Storage temperature range	-55 to 150		°C
T _J	Maximum operating junction temperature	150		°C

1. Limited by maximum junction temperature.
2. Pulse width limited by safe operating area.
3. I_{SD} ≤ 21 A, di/dt ≤ 400 A/μs, V_{DS} (peak) < V_{(BR)DSS}, V_{DD} = 400 V.

Table 2. Thermal data

Symbol	Parameter	Value				Unit
		D ² PAK	TO-220FP	TO-220	TO-247	
R _{thJC}	Thermal resistance, junction-to-case	0.83	3.6	0.83		°C/W
R _{thJA}	Thermal resistance, junction-to-ambient	30 ⁽¹⁾	62.5		50	°C/W

1. When mounted on a standard 1 inch² area of FR-4 PCB with 2-oz copper.

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I _{AR}	Avalanche current, repetitive or not-repetitive (pulse width limited by T _J max.)	7.5	A
E _{AS}	Single pulse avalanche energy (starting T _J = 25 °C, I _D = I _{AR} , V _{DD} = 50 V)	300	mJ

2 Electrical characteristics

$T_C = 25\text{ °C}$ unless otherwise specified.

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 1\text{ mA}$, $V_{GS} = 0\text{ V}$	500			V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$, $V_{DS} = 500\text{ V}$			1	μA
		$V_{GS} = 0\text{ V}$, $V_{DS} = 500\text{ V}$, $T_C = 125\text{ °C}^{(1)}$			100	
I_{GSS}	Gate body leakage current	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 25\text{ V}$			± 100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$	2	3	4	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}$, $I_D = 10.5\text{ A}$		135	158	m Ω

1. Specified by design, not tested in production.

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 25\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0\text{ V}$	-	1735	-	pF
C_{oss}	Output capacitance		-	122	-	pF
C_{rss}	Reverse transfer capacitance		-	4.3	-	pF
$C_{oss\text{ eq.}}^{(1)}$	Equivalent capacitance time related	$V_{DS} = 0\text{ to }50\text{ V}$, $V_{GS} = 0\text{ V}$	-	418	-	pF
Q_g	Total gate charge	$V_{DD} = 400\text{ V}$, $I_D = 21\text{ A}$, $V_{GS} = 0\text{ to }10\text{ V}$ (see the Figure 18. Test circuit for gate charge behavior)	-	50	-	nC
Q_{gs}	Gate-source charge		-	9.5	-	nC
Q_{gd}	Gate-drain charge		-	25	-	nC
R_g	Intrinsic gate resistance	$f = 1\text{ MHz}$, $I_D = 0\text{ A}$	-	2.7	-	Ω

1. $C_{oss\text{ eq.}}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS} .

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 250\text{ V}$, $I_D = 10.5\text{ A}$, $R_G = 4.7\text{ }\Omega$, $V_{GS} = 10\text{ V}$	-	13.6	-	ns
t_r	Rise time		-	19	-	ns
$t_{d(off)}$	Turn-off delay time	(see the Figure 17. Test circuit for resistive load switching times and Figure 22. Switching time waveform)	-	62	-	ns
t_f	Fall time		-	52	-	ns

Table 7. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		21	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		84	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 21\text{ A}$, $V_{GS} = 0\text{ V}$	-		1.5	V
t_{rr}	Reverse recovery time	$I_{SD} = 21\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 400\text{ V}$ (see the Figure 19. Test circuit for inductive load switching and diode recovery times)	-	326		ns
Q_{rr}	Reverse recovery charge		-	5		μC
I_{RRM}	Reverse recovery current		-	30		A
t_{rr}	Reverse recovery time	$I_{SD} = 21\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 400\text{ V}$, $T_J = 150\text{ }^\circ\text{C}$ (see the Figure 19. Test circuit for inductive load switching and diode recovery times)	-	376		ns
Q_{rr}	Reverse recovery charge		-	6.2		μC
I_{RRM}	Reverse recovery current		-	33.2		A

1. Pulse width limited by safe operating area.

2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%.

2.1 Electrical characteristics (curves)

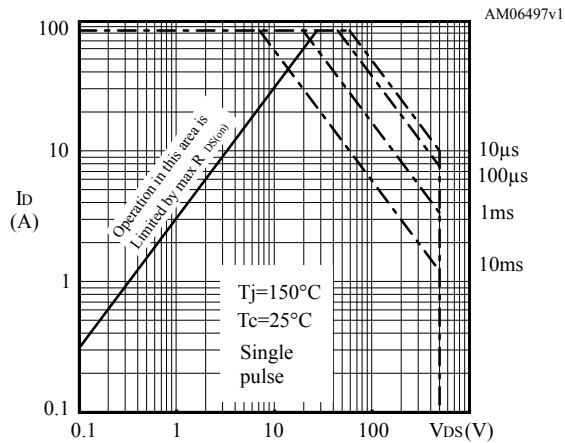
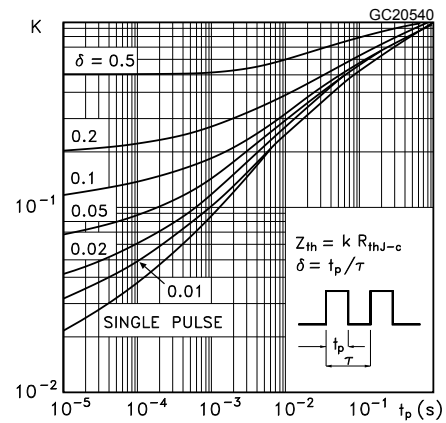
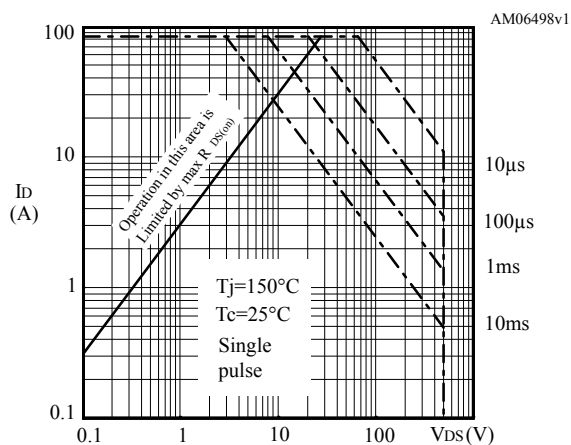
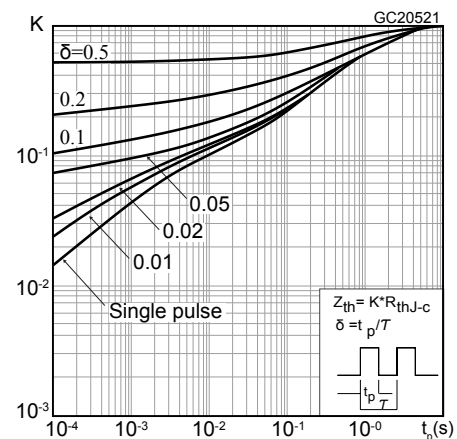
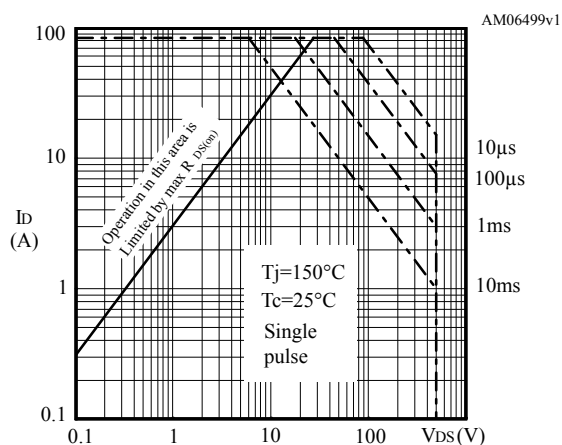
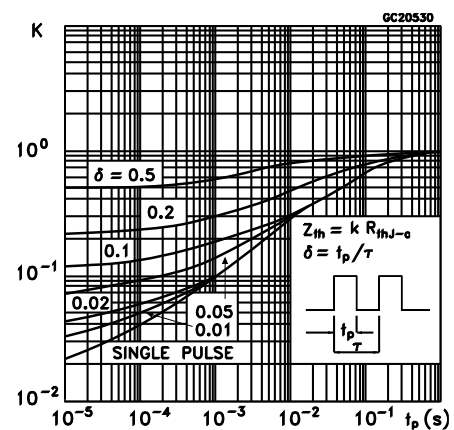
Figure 1. Safe operating area for D²PAK and TO-220

Figure 2. Normalized transient thermal impedance for D²PAK and TO-220

Figure 3. Safe operating area for TO-220FP

Figure 4. Normalized transient thermal impedance for TO-220FP

Figure 5. Safe operating area for TO-247

Figure 6. Normalized transient thermal impedance for TO-247


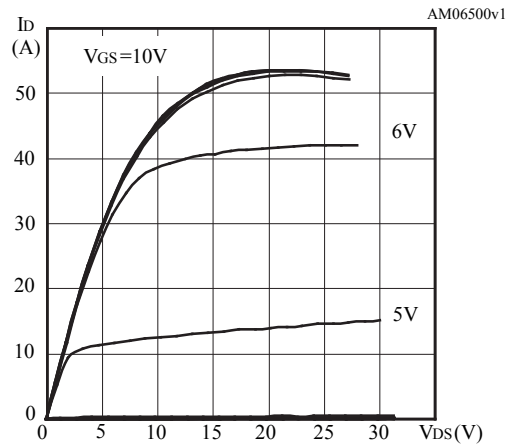
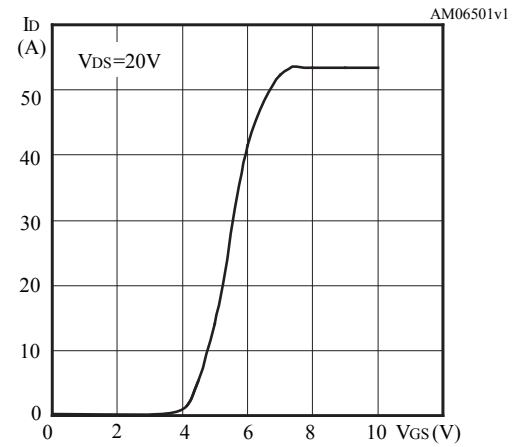
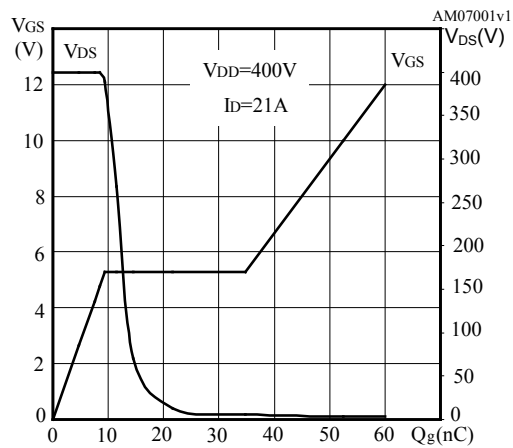
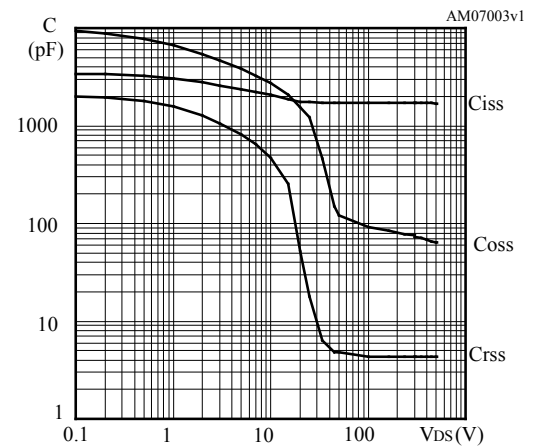
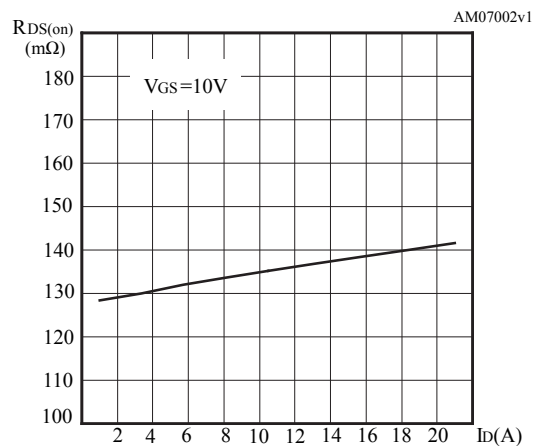
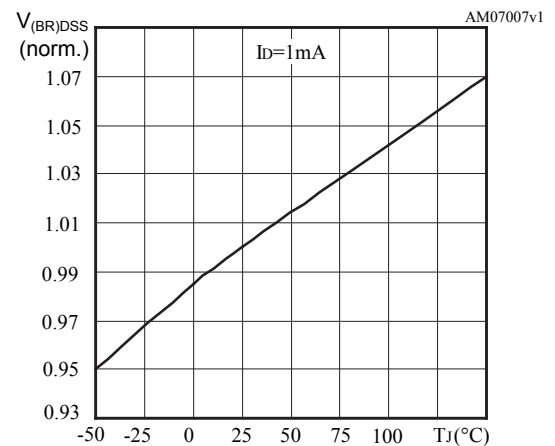
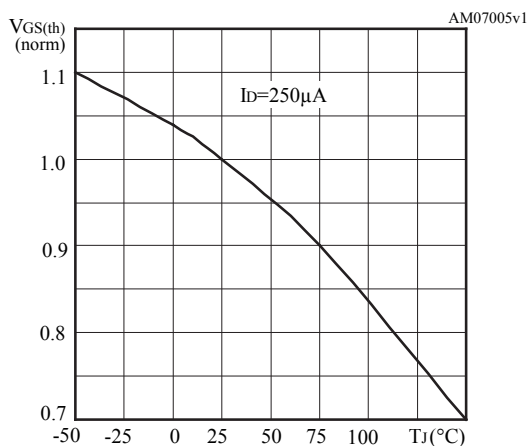
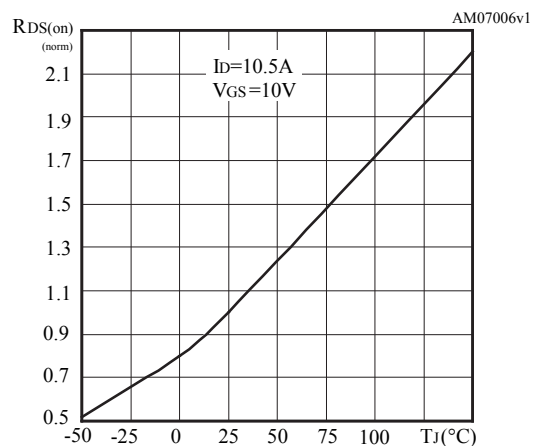
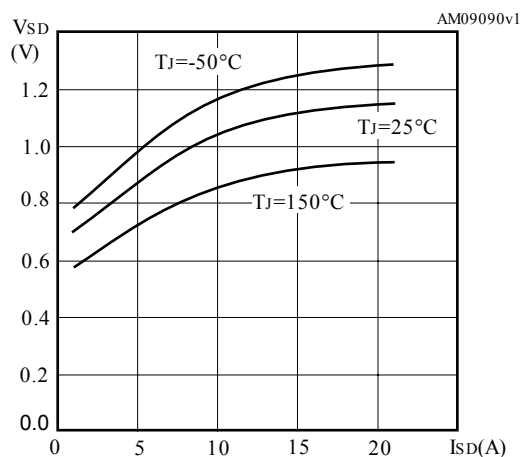
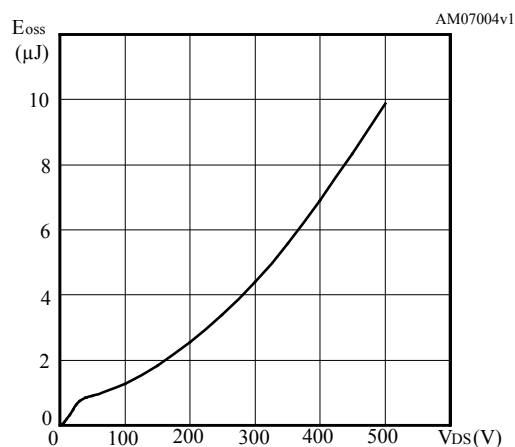
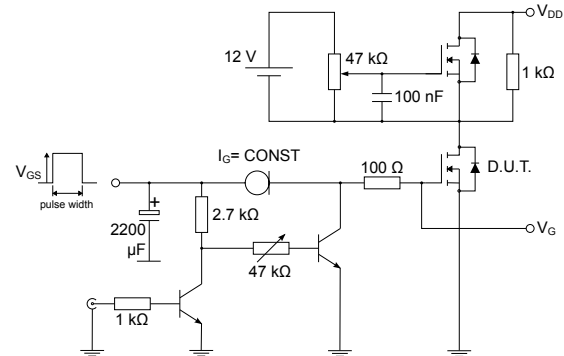
Figure 7. Typical output characteristics

Figure 8. Typical transfer characteristics

Figure 9. Typical gate charge characteristics

Figure 10. Typical capacitance characteristics

Figure 11. Typical drain-source on-resistance

Figure 12. Normalized breakdown voltage vs temperature


Figure 13. Normalized gate threshold vs temperature

Figure 14. Normalized on-resistance vs temperature

Figure 15. Typical reverse diode forward characteristics

Figure 16. Output capacitance stored energy


3 Test circuits

Figure 17. Test circuit for resistive load switching times


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Figure 18. Test circuit for gate charge behavior


AM01469v1

Figure 19. Test circuit for inductive load switching and diode recovery times

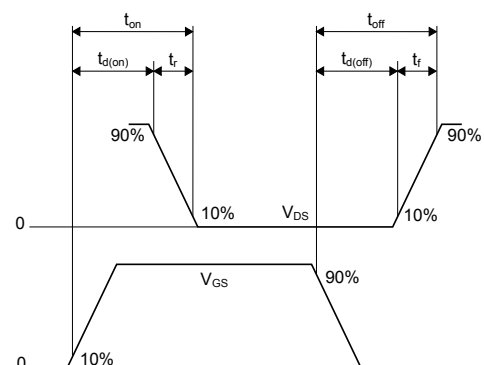

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Figure 20. Unclamped inductive load test circuit


AM01471v1

Figure 21. Unclamped inductive waveform


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Figure 22. Switching time waveform


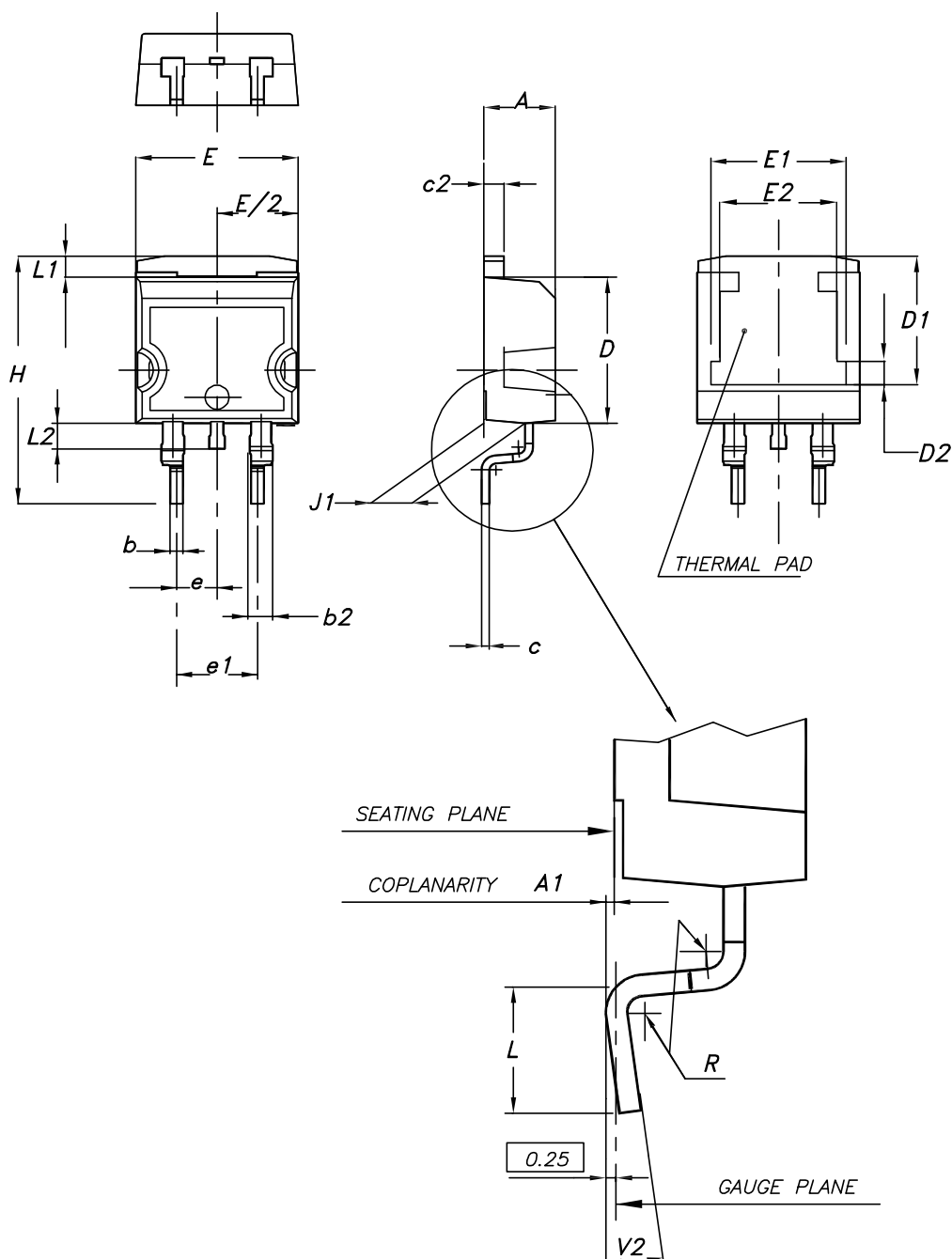
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4 Package information

To meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions, and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 D²PAK (TO-263) type A package information

Figure 23. D²PAK (TO-263) type A package outline

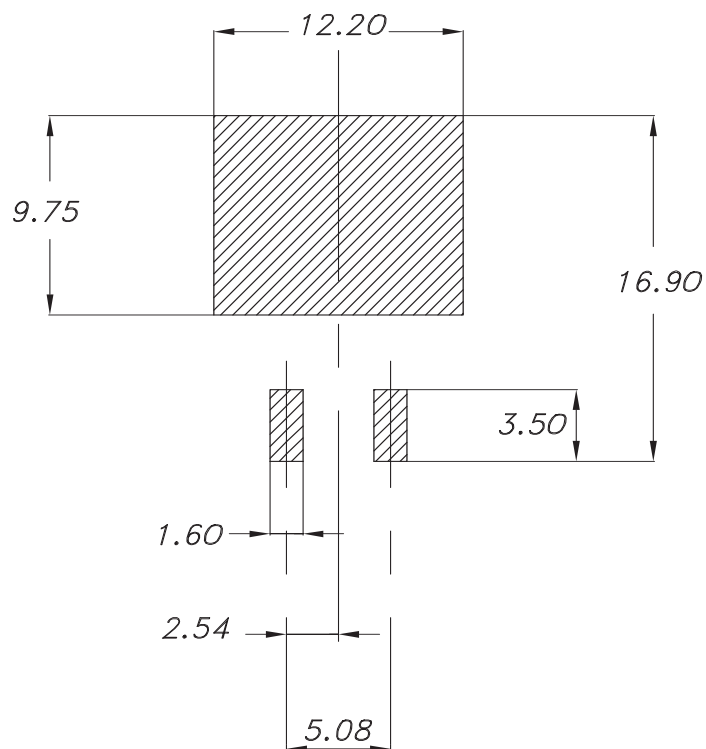


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Table 8. D²PAK (TO-263) type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10.00		10.40
E1	8.30	8.50	8.70
E2	6.85	7.05	7.25
e		2.54	
e1	4.88		5.28
H	15.00		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.40	
V2	0°		8°

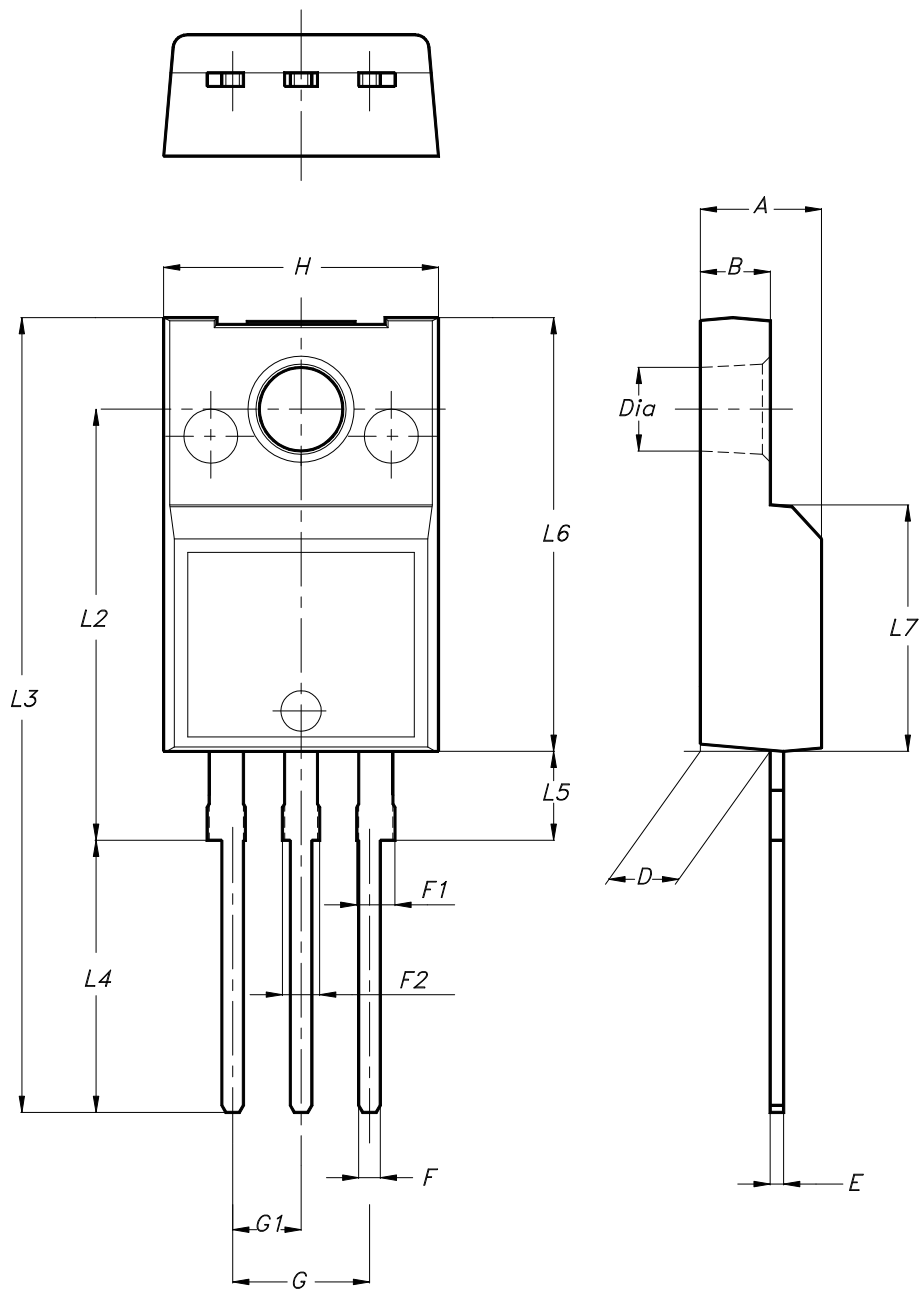
Figure 24. D²PAK (TO-263) recommended footprint (dimensions are in mm)



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4.2

Figure 25. TO-220FP type B package outline



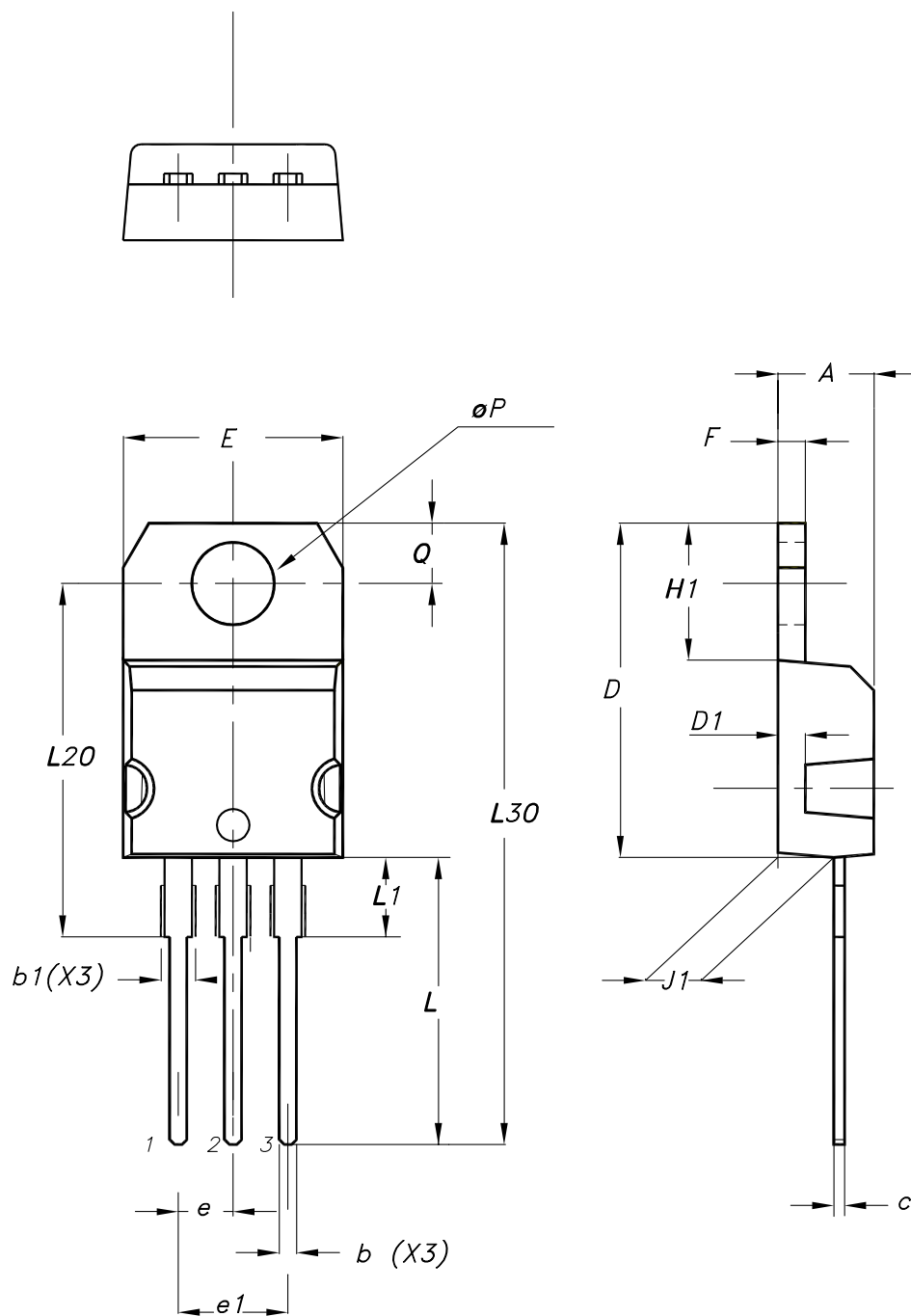
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Table 9. TO-220FP type B package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
B	2.50		2.70
D	2.50		2.75
E	0.45		0.70
F	0.75		1.00
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.20
G1	2.40		2.70
H	10.00		10.40
L2		16.00	
L3	28.60		30.60
L4	9.80		10.60
L5	2.90		3.60
L6	15.90		16.40
L7	9.00		9.30
Dia	3.00		3.20

4.3 TO-220 type A package information

Figure 26. TO-220 type A package outline



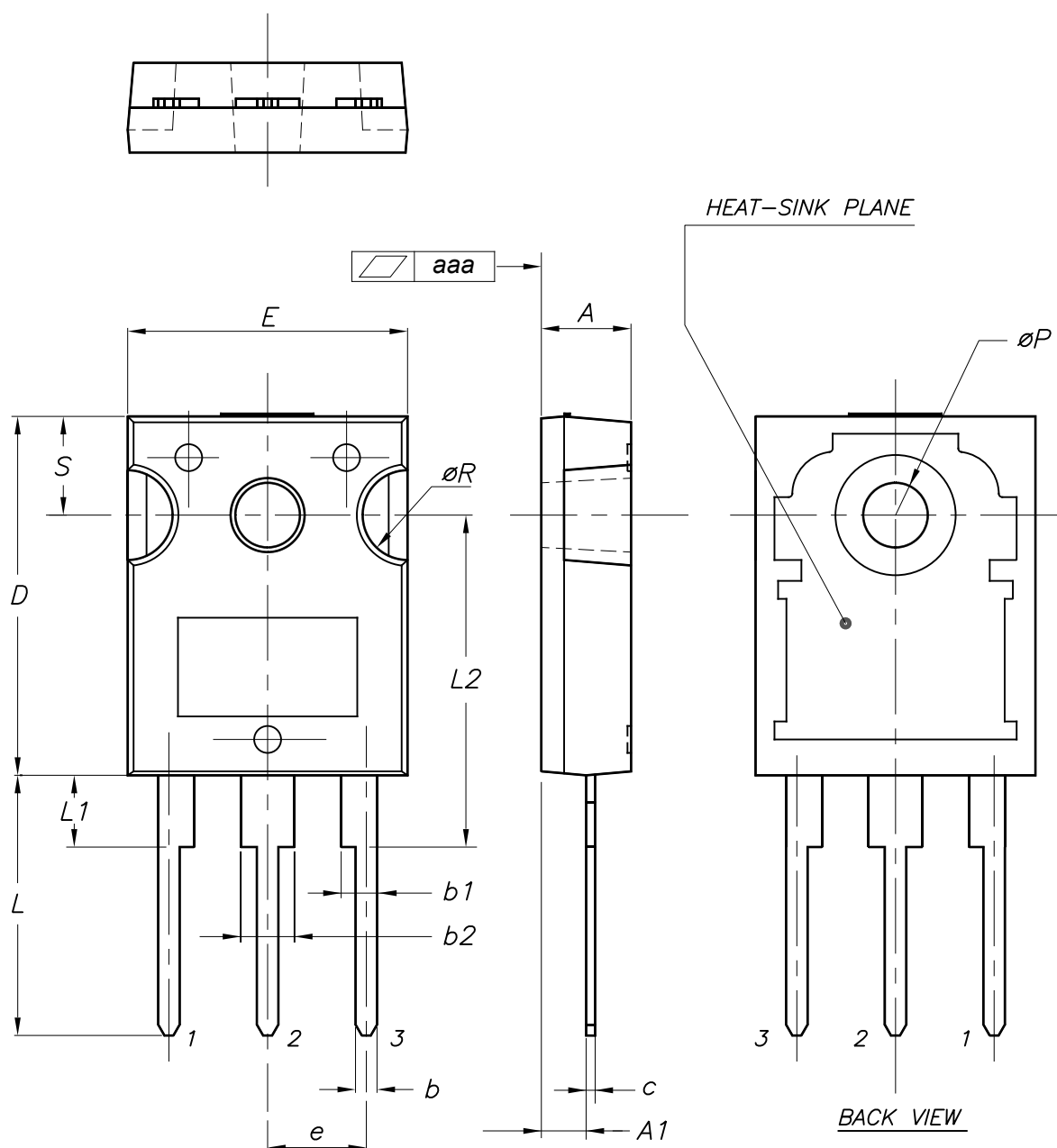
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Table 10. TO-220 type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95
Slug flatness		0.03	0.10

4.4 TO-247 package information

Figure 27. TO-247 package outline



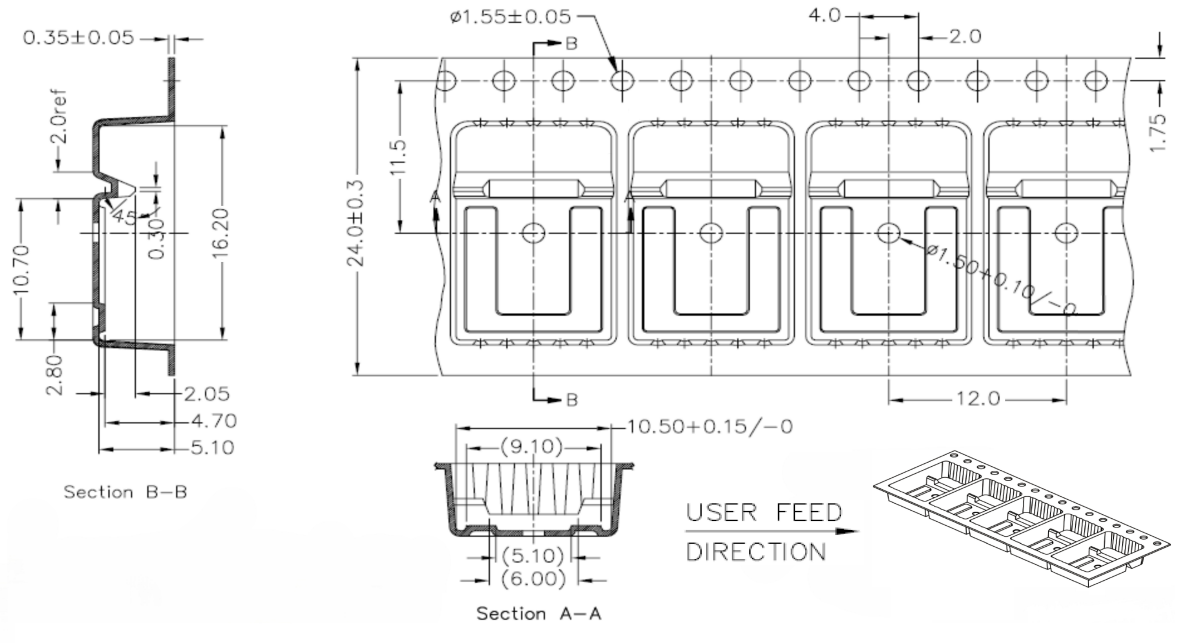
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Table 11. TO-247 package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70
aaa		0.04	0.10

4.5 D²PAK packing information

Figure 28. D²PAK tape drawing (dimensions are in mm)



DM01095771_2



5 Ordering information

Table 12. Order codes

Order codes	Marking	Package	Packing
STB28NM50N	28NM50N	D ² PAK	Tape and reel
STF28NM50N		TO-220FP	Tube
STP28NM50N		TO-220	
STW28NM50N		TO-247	

Revision history

Table 13. Document revision history

Date	Revision	Changes
19-Jul-2010	1	First release.
27-Jun-2011	2	– Updated <i>Table 6: Dynamic</i>. – Updated <i>Section 2.1: Electrical characteristics (curves)</i>.
18-Sep-2025	3	Updated Section 4: Package information . Minor text changes.



Contents

1	Electrical ratings	2
2	Electrical characteristics	3
2.1	Electrical characteristics (curves)	5
3	Test circuits	8
4	Package information	9
4.1	D ² PAK (TO-263) type A package information	9
4.2	TO-220FP type B package information	12
4.3	TO-220 type A package information	14
4.4	TO-247 package information	16
4.5	D ² PAK packing information	18
5	Ordering information	19
	Revision history	20



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